

## WORLD'S SMALLEST CLASS, FOUR CHANNELS 12-PIN ULTRA SHRINK SOP PHOTOCOUPLER

–NEPOC Series–

### DESCRIPTION

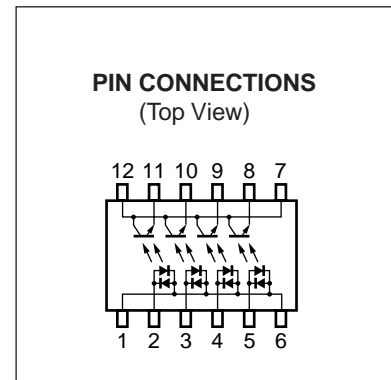
The PS2845-4A is an optically coupled isolator containing GaAs light emitting diodes and NPN silicon phototransistors.

This product includes four channels in a single package for high-density mounting applications.

The PS2845-4A is the world's smallest class of photocouplers and realizes about 50% reduction in mounting area compared with the PS280x and PS281x Series.

### FEATURES

- Ultra small and thin package  
(12-pin ultra shrink SOP, Pin pitch 0.8 mm, 4.4 (L) × 5.6 (W) × 2.5 (H))
- Common lead anode, cathode, collector common
- High current transfer ratio (CTR = 200% TYP. @  $I_F = \pm 1\text{mA}$ )
- High isolation voltage (BV = 1 500 Vr.m.s.)
- Pb-Free product
- Ordering number of tape product: PS2845-4A-F3, F4: 2 500 pcs/reel
- Safety standards
  - UL approved: File No. E72422



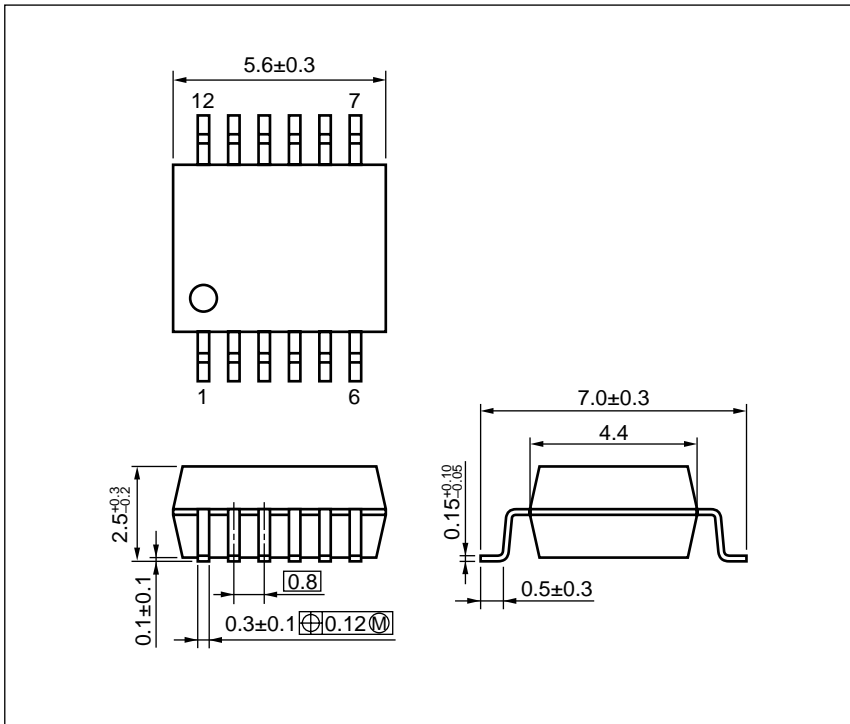
### APPLICATIONS

- Programmable logic controllers (PLCs)
- Input and output for function automation
- Hybrid IC

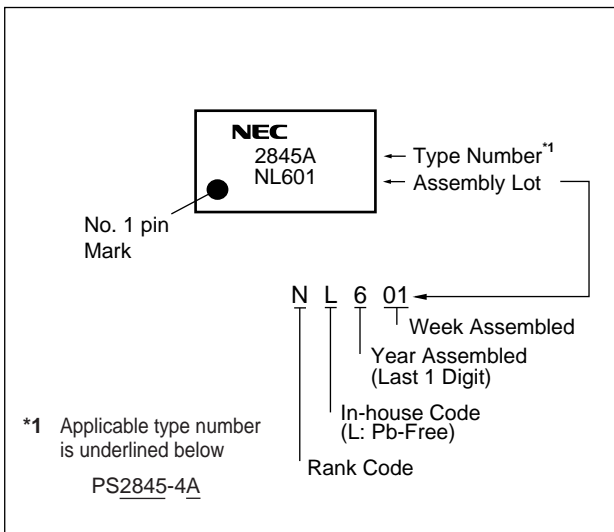
Channel	Anode, Cathode	Cathode, Anode	Emitter	Collector
1 ch	1, 6 common	2	11	7, 12 common
2 ch	1, 6 common	3	10	7, 12 common
3 ch	1, 6 common	4	9	7, 12 common
4 ch	1, 6 common	5	8	7, 12 common

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**PACKAGE DIMENSIONS (UNIT: mm)**



**<R> MARKING EXAMPLE**



<R> **ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS2845-4A-F3	PS2845-4A-F3-A	Pb-Free	Embossed Tape 2 500 pcs/reel	Standard products (UL Approved)	PS2845-4A
PS2845-4A-F4	PS2845-4A-F4-A				

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I <sub>F</sub>	±20	mA/ch
	Power Dissipation Derating	ΔI <sub>F</sub> /°C	0.2	mA/°C
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	±0.5	A/ch
Transistor	Collector to Emitter Voltage	V <sub>CEO</sub>	70	V
	Emitter to Collector Voltage	V <sub>ECO</sub>	5	V
	Collector Current	I <sub>C</sub>	20	mA/ch
	Power Dissipation Derating	ΔP <sub>C</sub> /°C	0.4	mW/°C
	Power Dissipation	P <sub>C</sub>	40	mW/ch
Isolation Voltage <sup>*2</sup>		BV	1 500	Vr.m.s.
Operating Ambient Temperature		T <sub>A</sub>	-40 to +100	°C
Storage Temperature		T <sub>stg</sub>	-55 to +125	°C

\*1 PW = 100 μs, Duty Cycle = 1%

\*2 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output.  
Pins 1-6 shorted together, 7-12 shorted together.

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = ±1 mA	0.9	1.1	1.2	V
	Terminal Capacitance	C <sub>t</sub>	V = 0 V, f = 1 MHz		30		pF
Transistor	Collector to Emitter Current	I <sub>CEO</sub>	I <sub>F</sub> = 0 mA, V <sub>CE</sub> = 24 V			100	nA
Coupled	Current Transfer Ratio (I <sub>c</sub> /I <sub>F</sub> )	CTR	I <sub>F</sub> = ±1 mA, V <sub>CE</sub> = 0.4 V	100	200	400	%
	Optical Leakage Current <sup>*1</sup> (1 to 2-ch, 2 to 3-ch, 3 to 4-ch)	I <sub>L</sub>	I <sub>F</sub> = 5 mA, V <sub>CE</sub> = 24 V			100	nA
	Collector Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> = ±1 mA, I <sub>c</sub> = 0.2 mA		0.13	0.3	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kV <sub>DC</sub>	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Turn-on Time <sup>*2</sup>	t <sub>on</sub>	V <sub>CC</sub> = 5 V, I <sub>F</sub> = ±1 mA, R <sub>L</sub> = 5 kΩ		20		μs
	Turn-off Time <sup>*2</sup>	t <sub>off</sub>			110		

\*1 The optically induced leakage current is current which can be measured at transistor if LED = "ON" and LED = "OFF".

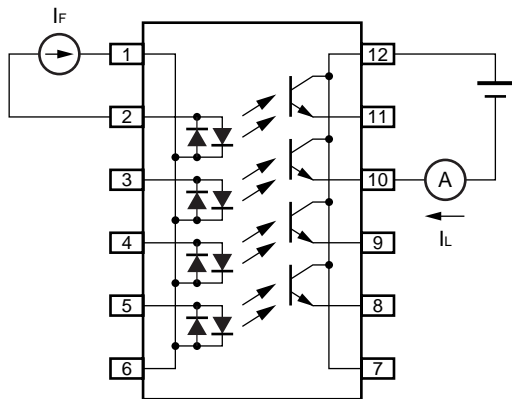
LED of channel 1 is switched to "ON".

At Tr-output of channel 2 a voltage is applied and one can measure a current between emitter and collector.

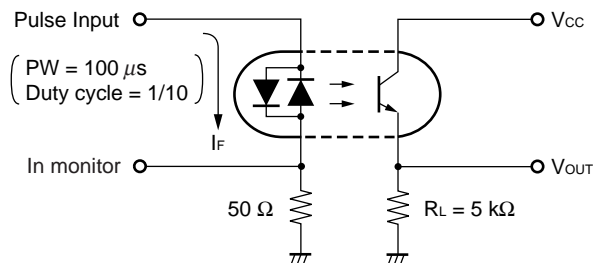
This is leakage current (at I<sub>F</sub> = 5 mA, V<sub>CEO</sub> = 24 V).

Measurement circuits for optical leakage current

E.g. : In the case of 1 to 2-ch

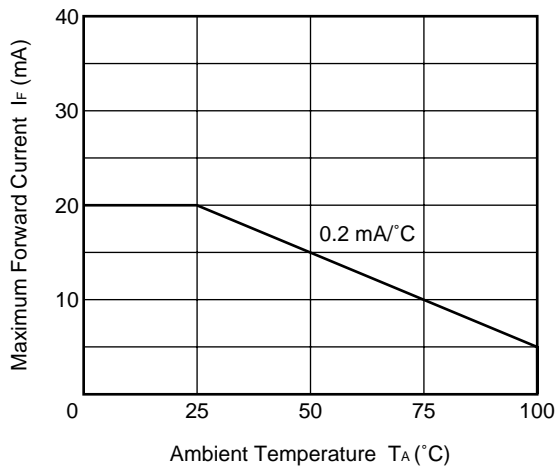


\*2 Test circuit for switching time

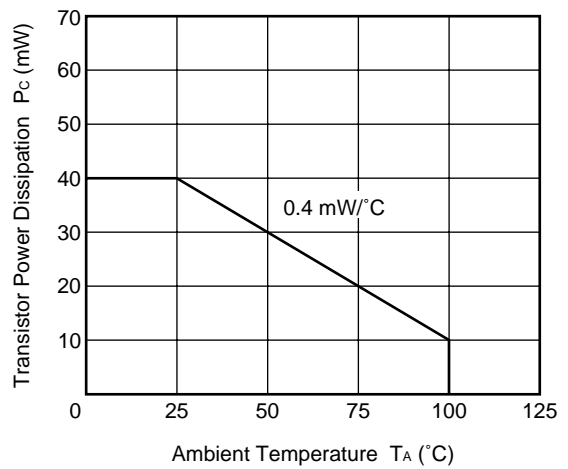


**TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**

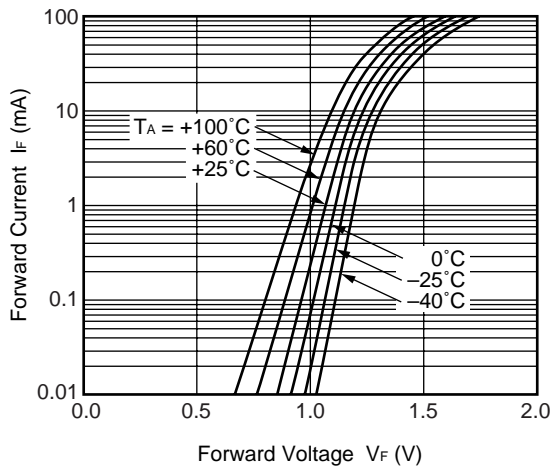
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



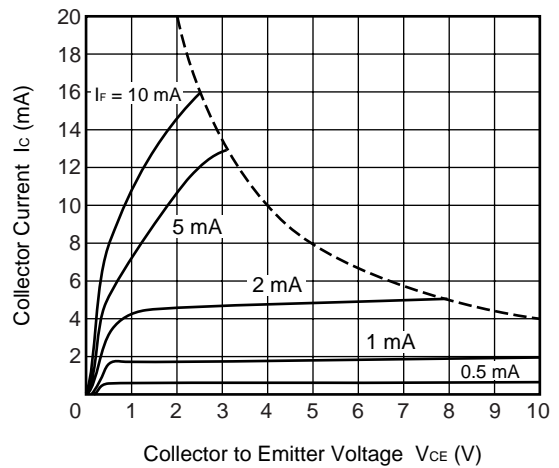
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



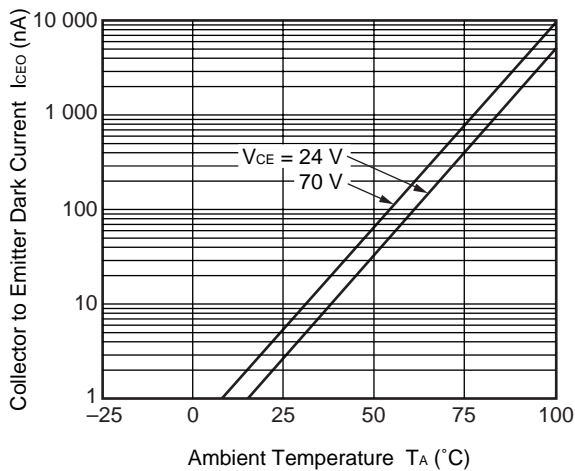
FORWARD CURRENT vs. FORWARD VOLTAGE



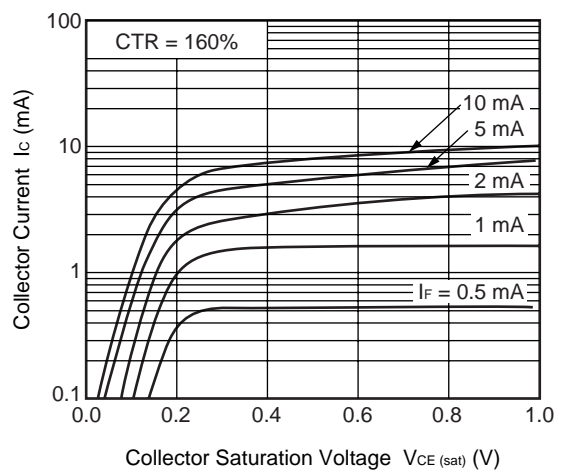
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

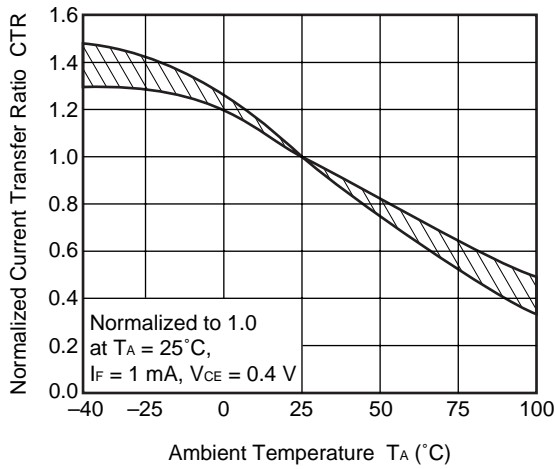


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

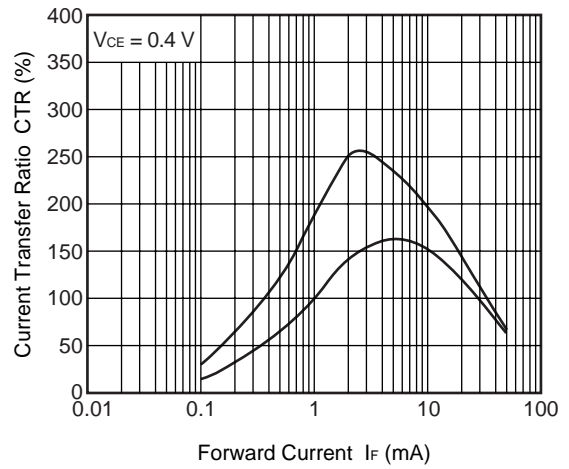


**Remark** The graphs indicate nominal characteristics.

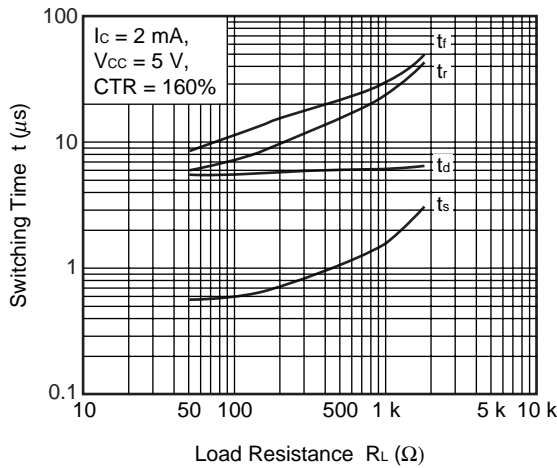
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



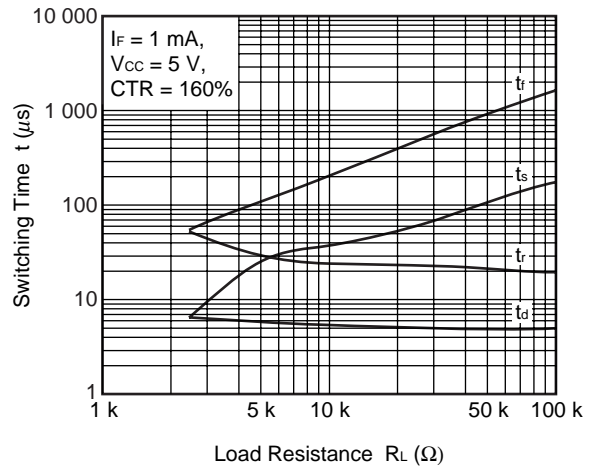
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



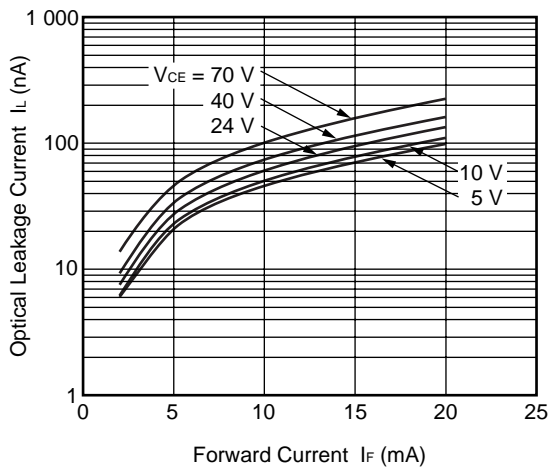
SWITCHING TIME vs. LOAD RESISTANCE



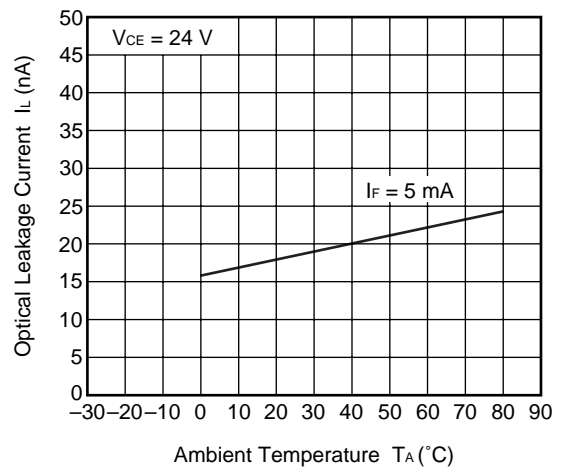
SWITCHING TIME vs. LOAD RESISTANCE



OPTICAL LEAKAGE CURRENT vs. FORWARD CURRENT



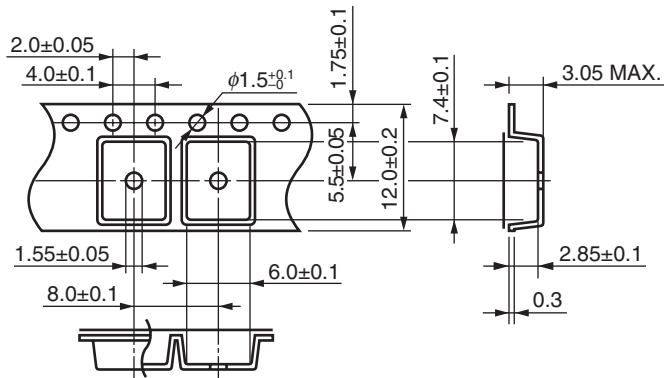
OPTICAL LEAKAGE CURRENT vs. AMBIENT TEMPERATURE



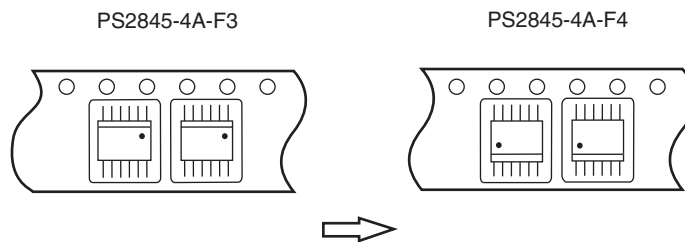
**Remark** The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

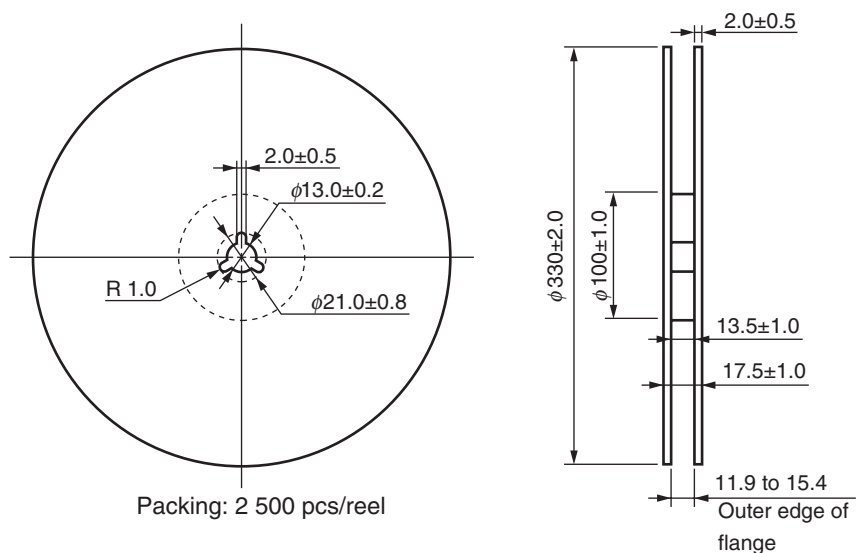
Outline and Dimensions (Tape)



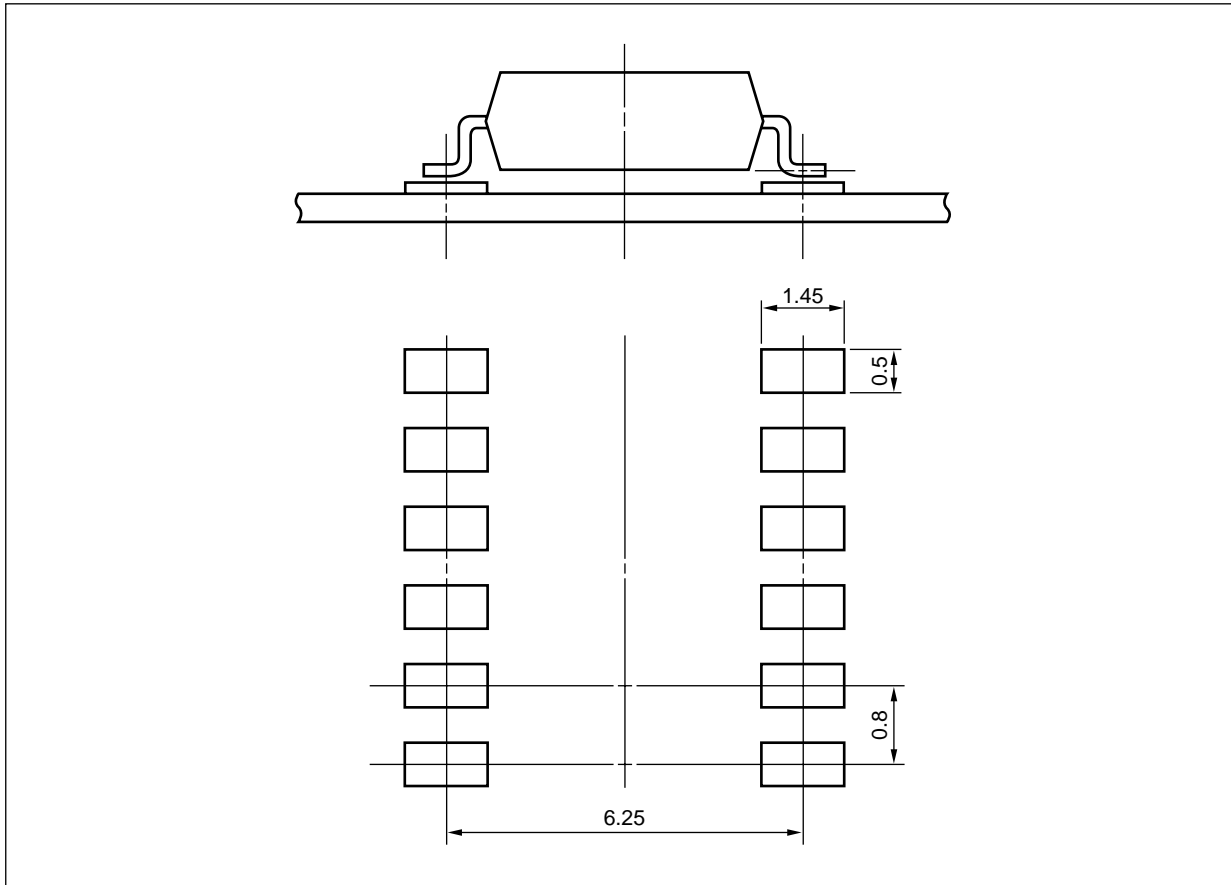
Tape Direction



Outline and Dimensions (Reel)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)





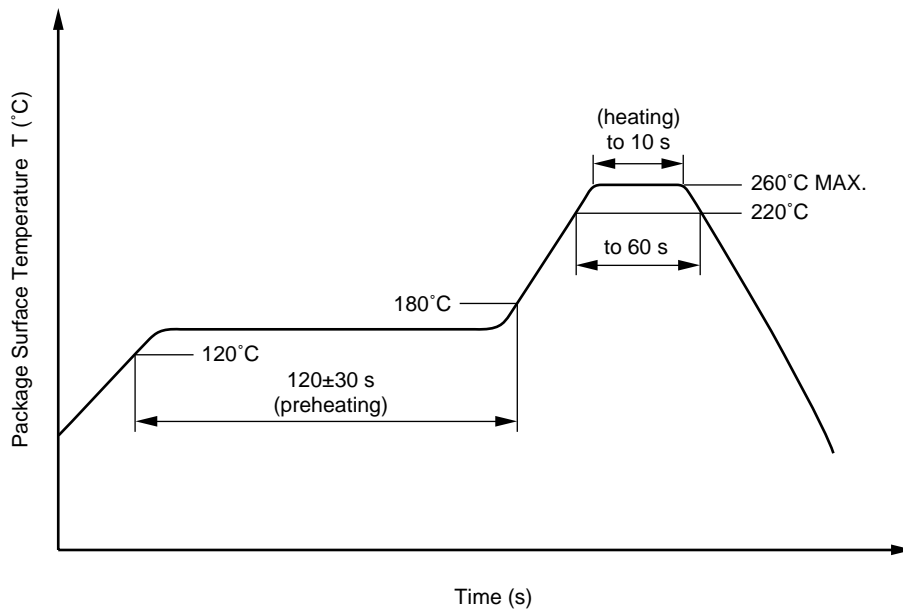
**NOTES ON HANDLING**

**1. Recommended soldering conditions**

**(1) Infrared reflow soldering**

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



**(2) Wave soldering**

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

**(3) Soldering by soldering iron**

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

**(4) Cautions**

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

**2. Cautions regarding noise**

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

**<R> 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler**

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

**USAGE CAUTIONS**

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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<p><b>Caution</b></p>	<p>GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> <li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.             <ol style="list-style-type: none"> <li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> <li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li> </ol> </li> <li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li> <li>• Do not lick the product or in any way allow it to enter the mouth.</li> </ul>
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► For further information, please contact

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